



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

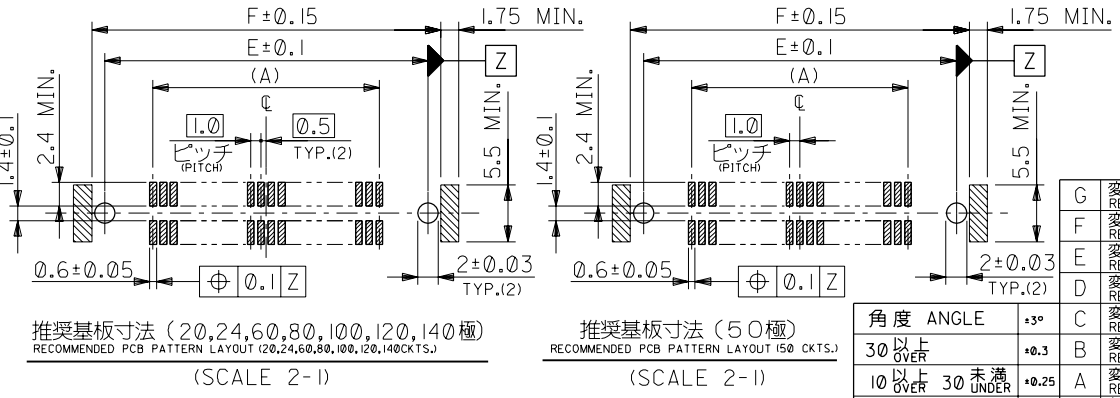
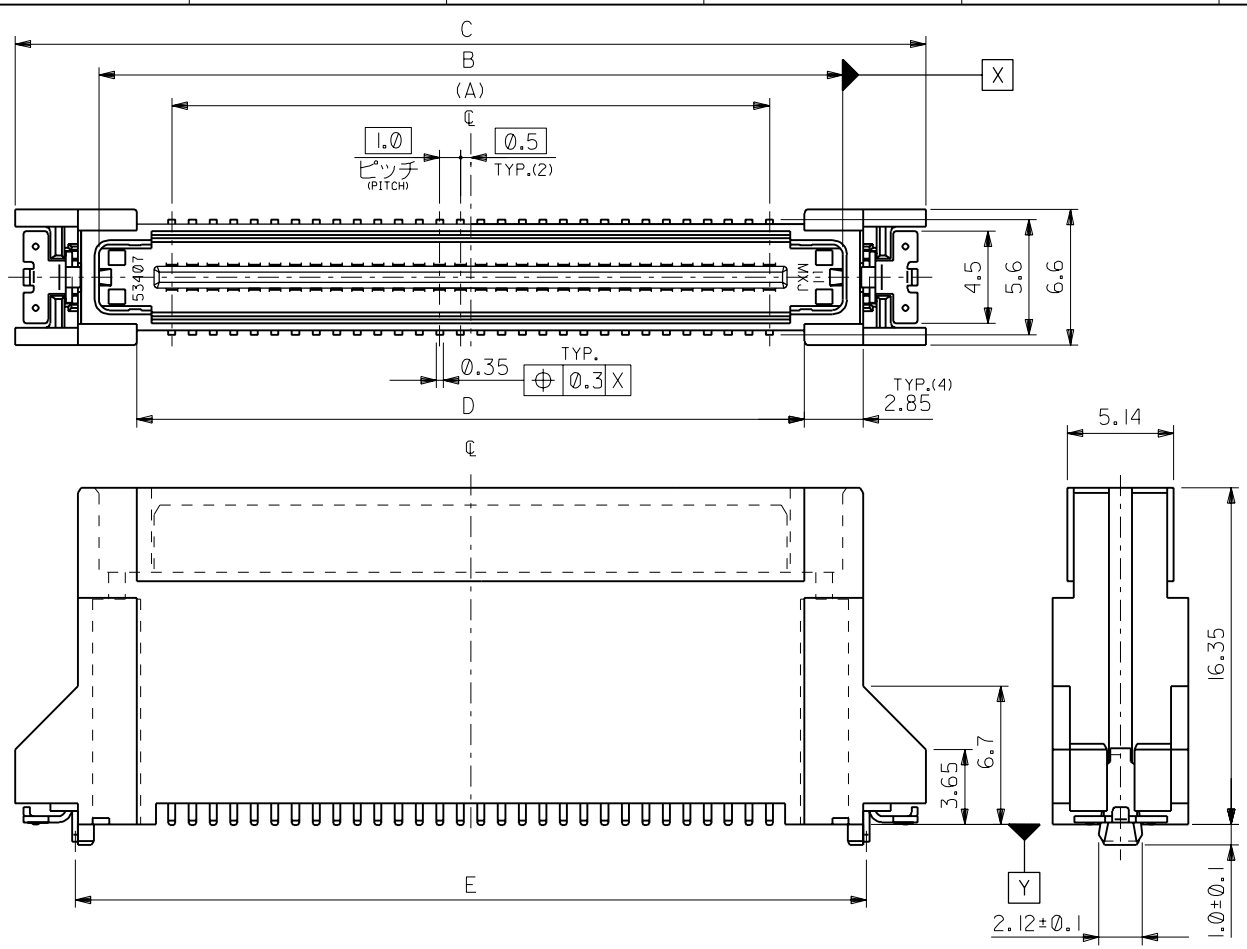
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DWG. NO. SD-53408-\*\*\*0

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



推奨基板寸法 (20, 24, 60, 80, 100, 120, 140極)  
RECOMMENDED PCB PATTERN LAYOUT (20, 24, 60, 80, 100, 120, 140CKTS.)  
(SCALE 2-1)

推奨基板寸法 (50極)  
RECOMMENDED PCB PATTERN LAYOUT (50 CKTS.)  
(SCALE 2-1)

|                           |       |
|---------------------------|-------|
| 角度 ANGLE                  | ±3°   |
| 30°以上 OVER                | ±0.3  |
| 10°以上 OVER 30°未滿 UNDER    | ±0.25 |
| 未滿 UNDER                  | ±0.2  |
| ① 新規作成 RELEASED           |       |
| ② 変更内容 REVISION RECORD    |       |
| ③ 一般公差 GENERAL TOLERANCES |       |

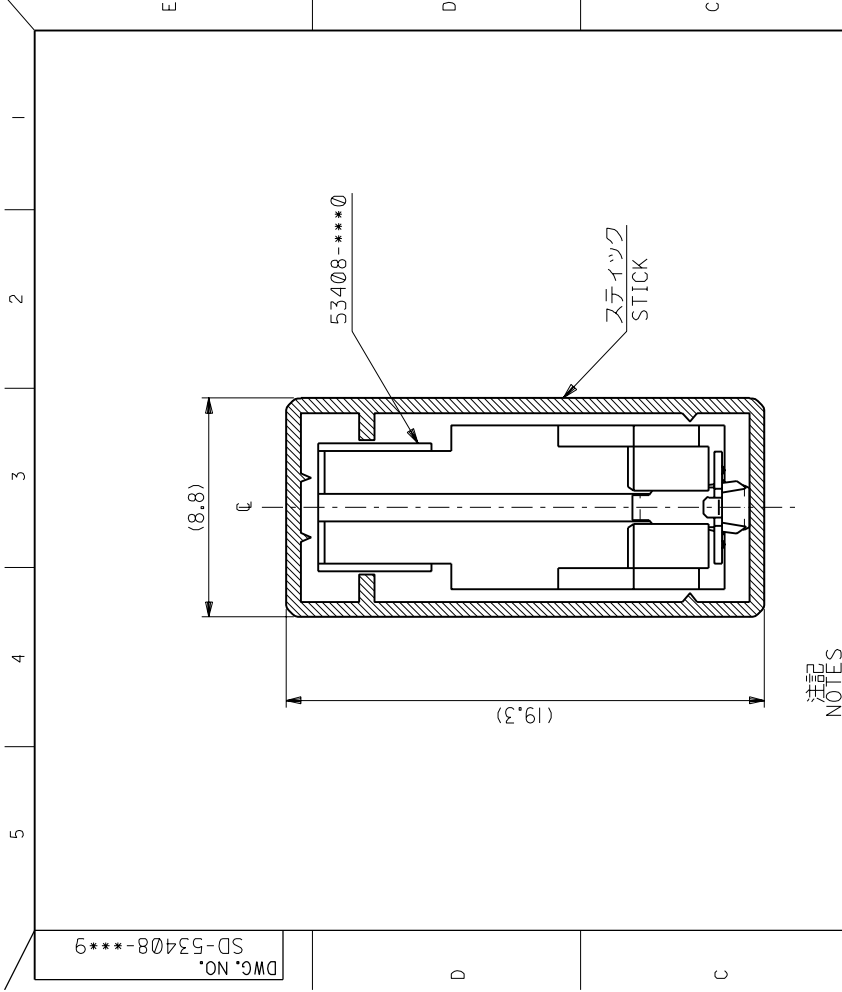
|        |                      |               |          |         |           |
|--------|----------------------|---------------|----------|---------|-----------|
| G      | 変更 REVISION          | (JD2001-1424) | T.H.     | T.H.    | 10/24/19  |
| F      | 変更 REVISION          | (JD60150)     | J.M.     | Y.I.    | 195/08/10 |
| E      | 変更 REVISION          | (T40044)      | S.A.     | J.M.    | 194/01/27 |
| D      | 変更 REVISION          | (T30585)      | S.M.     | M.S.    | 193/12/1  |
| C      | 変更 REVISION          | (T30434)      | S.M.     | S.I.    | 193/9/8   |
| B      | 変更 REVISION          | (T30355)      | J.M.     | Y.I.    | 193/7/15  |
| A      | 変更 REVISION          | (T30275)      | S.M.     | M.S.    | 193/6/8   |
| ①      | 新規作成 RELEASED        |               | H.H.     | M.S.    | 193/2/18  |
| 記号 LTR | 変更内容 REVISION RECORD |               | DR. CHK. | 日付 DATE |           |

|                   |               |
|-------------------|---------------|
| 材料 MATERIAL       | 注参照 SEE NOTES |
| 仕上げ FINISH        | 注参照 SEE NOTES |
| 適用電線範囲 WIRE RANGE | —             |
| 被覆外径 INS. RANGE   | —             |
| DRAWN BY          | CHK'D BY      |
| APP'D BY          | 尺度 SCALE      |

|  |     |
|--|-----|
| molex MOLEX-JAPAN CO., LTD.<br>日本モレックス株式会社 |     |
| REVISE ONLY ON CAD SYSTEM                  |     |
| TITLE 名称                                   |     |
| 1.0 B-T-O-B<br>S/T PLUG HS'G ASS'Y         |     |
| DWG. NO.                                   | REV |
| SD-53408-***0                              | G   |

- 注) 1. 材質 MATERIAL  
ハウジング: ガラス入りLCP、白色、UL94V-0  
ターミナル: 燐青銅 (t=0.2)  
TERMINAL: PHOSPHOR BRONZE  
金属ペグ: 燐青銅  
METAL PEG: PHOSPHOR BRONZE
2. ヌッキ仕様 PLATING  
ターミナル 接点部: 金メッキ0.25 μmMIN.  
TERMINAL CONTACT AREA: GOLD 0.25 μmMIN.  
半田付け部: 半田メッキ1.0 μmMIN.  
SOLDER TAIL AREA: TIN-LEAD 1.0 μmMIN.  
下地メッキ: ニッケルメッキ 2.0 μmMIN.  
UNDER-PLATING: NICKEL 2.0 μmMIN.  
金属ペグ 半田付け部: 半田メッキ 3.5 μmMIN.  
METAL PEG SOLDER TAIL AREA: TIN-LEAD 3.5 μmMIN.
3. 推奨基板厚 RECOMMENDED PCB THICKNESS  
1.0±0.1mm MIN.
4. テールのバラツキ寸法 TAIL COPLANARITY  
テールは、Y面を基準とし、上へ0.02 下へ0.15の範囲にのみ、且つテール平坦度は0.15とする。  
TAILS TO BE WITHIN 0.02 UPWARD AND 0.15 DOWNWARD FROM Y-DATUM PLANE, AND TAIL COPLANARITY TO BE 0.15.
5. ロックは、20、24、50極に設置する。  
LOCK TO BE ADDED TO 20, 24 AND 50 CKTS.
- 
6. 梱包 PACKAGING  
本製品はスティック梱包とし梱包後のENG. NO. は53408-\*\*\*9とする。  
THIS PRODUCTS TO BE PACKED IN TUBE. ENG. NO.: 53408-\*\*\*9
7. 同一基板内に複数個 (2ヶ以上) の使用は避けてください。  
MXJ DOES NOT RECOMMEND THE USAGE OF TWO OR MORE OF THESE CONNECTORS BETWEEN A SINGLE PAIR OF P.C.BOARD.

|      |      |      |      |       |     |            |                 |
|------|------|------|------|-------|-----|------------|-----------------|
| 80.9 | 78.4 | 72.4 | 84.2 | 76.02 | 69  | 53408-1400 | 140             |
| 70.9 | 68.4 | 62.4 | 74.2 | 66.02 | 59  | 53408-1200 | 120             |
| 60.9 | 58.4 | 52.4 | 64.2 | 56.02 | 49  | 53408-1000 | 100             |
| 50.9 | 48.4 | 42.4 | 54.2 | 46.02 | 39  | 53408-0800 | 80              |
| 40.9 | 38.4 | 32.4 | 44.2 | 36.02 | 29  | 53408-0600 | 60              |
| 35.9 | 33.4 | 27.4 | 39.2 | 31.02 | 24  | 53408-0500 | 50              |
| 22.9 | 20.4 | 14.4 | 26.2 | 18.02 | 11  | 53408-0240 | 24              |
| 20.9 | 18.4 | 12.4 | 24.2 | 16.02 | 9   | 53408-0200 | 20              |
| F    | E    | D    | C    | B     | (A) | ENG. NO.   | 種数 NO. OF CKTS. |



DWG. NO. SD-53408-\*\*\*9

A DIMENSIONS IN METRIC DO NOT SCALE DRAWING

|    |            |     |
|----|------------|-----|
| 6  | 53408-1409 | 140 |
| 7  | 53408-1209 | 120 |
| 8  | 53408-1009 | 100 |
| 10 | 53408-0809 | 80  |
| 13 | 53408-0609 | 60  |
| 14 | 53408-0509 | 50  |
| 21 | 53408-0249 | 24  |
| 23 | 53408-0209 | 20  |

|      |       |       |
|------|-------|-------|
| 角度   | ANGLE | ±3°   |
| 30以上 | OVER  | +0.3  |
| 10以上 | UNDER | +0.25 |
| 10以下 | UNDER | +0.2  |

一般公差 GENERAL TOLERANCES

|   |      |                     |       |          |
|---|------|---------------------|-------|----------|
| G | 変更   | (JIS B 0200-1-1624) | K.T.H | 01/04/79 |
| F | 変更   | (JIS B 0150)        | M.V.I | 05/08/78 |
| E | 変更   | (JIS B 0648)        | S.V.J | 03/12/74 |
| D | 変更   | (JIS B 0585)        | S.J.M | 03/12/71 |
| C | 変更   | (JIS B 0585)        | S.M.S | 03/11/75 |
| B | 変更   | (JIS B 0434)        | S.S.T | 03/12/78 |
| A | 変更   | (JIS B 0275)        | S.M.S | 03/16/78 |
| 0 | 新規作成 | (JIS B 010)         | S.M.S | 03/12/73 |

|          |            |          |
|----------|------------|----------|
| 材料       | MATERIAL   | 01/04/79 |
| スティック    | ポリ塩化ビニル    | 05/08/78 |
| スティック    | P.V.C.     | 03/12/74 |
| 仕上げ      | FINISH     | 03/12/71 |
| 適用電線範囲   | WIRE RANGE | 03/11/75 |
| 液層外径     | INS. RANGE | 03/12/78 |
| 液層内径     | INS. RANGE | 03/16/78 |
| DRAWN BY | CHK'D BY   | 03/12/73 |
| J. Inoue | /I. Inoue  |          |
| APP'D BY | SCALE      | 5-1      |
| 日付       | DATE       |          |

家内書 REVISION RECORD

家内書 REV

注記 NOTES

- スティック両端はキャップ止め。 BOTH ENDS WITH CAPS.
- 全長: 600±2 TOTAL LENGTH
- 肉厚: 0.6±0.2 THICKNESS

|                           |               |              |
|---------------------------|---------------|--------------|
| 数量                        | ENG. NO.      | 数量           |
| MOLEX-JAPAN CO.,LTD.      |               | NO. OF CKTS. |
| 日本モロックス株式会社               |               |              |
| REVISE ONLY ON CAD SYSTEM |               |              |
| TITLE 名称                  |               |              |
| 53408-***0                |               |              |
| STICK PACKAGING           |               |              |
| DWG. NO.                  | SD-53408-***9 | REV          |
|                           |               | G            |

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